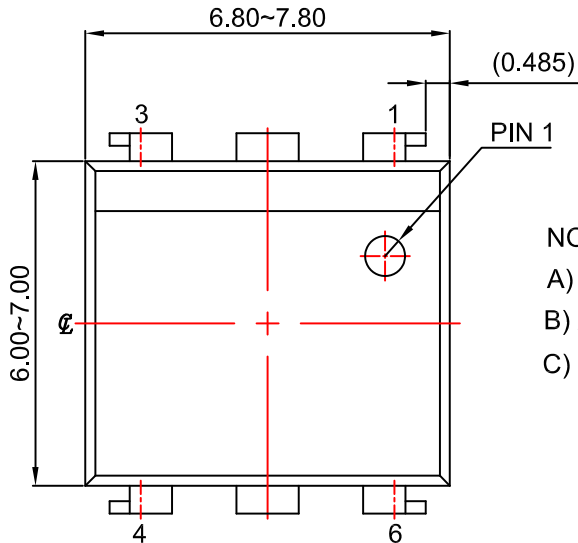


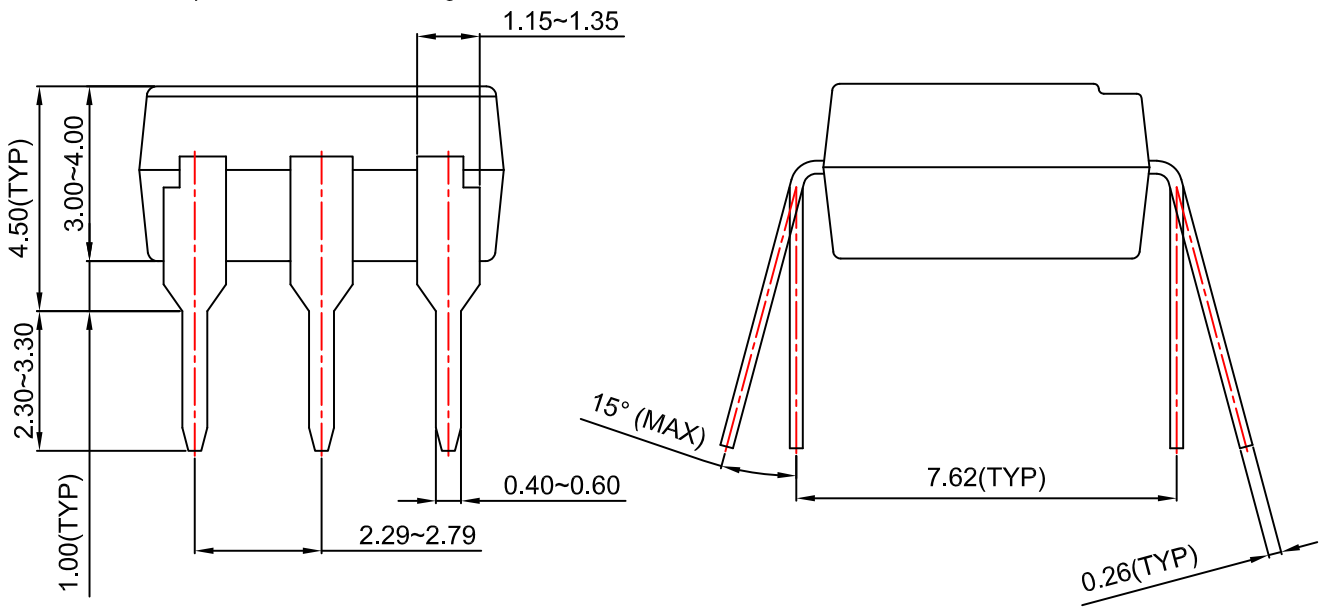
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**PDIP6 GW**  
**CASE 709AG**  
**ISSUE A**

DATE 31 JUL 2016



- NOTES:
- A) NO STANDARD APPLIES TO THIS PACKAGE.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION



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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>PDIP6 GW</b>	<b>PAGE 1 OF 2</b>

